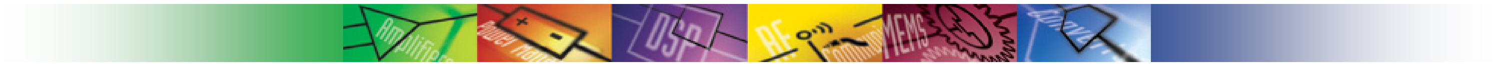

Product / Package Information

Package	LFCSP - Punched
Body Size (mm)	5 X 5 X 0.85 (3.1 EP)
Lead Count	16
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.18E-02	86.91	869100	33.68	336763
Thermosets	Epoxy & Phenol Resin	Proprietary	3.21E-03	12.78	127800	4.95	49521
Other inorganic materials	Carbon black	1333-86-4	7.79E-05	0.31	3100	0.12	1201
Subtotal			2.51 E-02	100.00	1000000	38.75	387485

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.23 E-02	96.40	963989	49.74	497447
Copper & its alloys	Iron	7439-89-6	8.37 E-04	2.50	25006	1.29	12904
Copper & its alloys	Zinc	7440-66-6	2.01 E-04	0.60	6004	0.31	3098
Copper & its alloys	Phosphorus	7723-14-0	1.67 E-04	0.50	5001	0.26	2581
Subtotal			3.35 E-02	100.00	1000000	51.60	516030

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.40 E-04	100.0	1000000	1.14	11406

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.09 E-03	100.0	1000000	1.68	16800

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.40 E-04	100.0	1000000	0.83	8323

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.18 E-03	100.0	1000000	4.90	49014

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.52 E-04	77.71	777100	0.85	8504
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	2.21 E-05	3.11	31100	0.03	340
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	2.21 E-05	3.11	31100	0.03	340
Other organic materials	Butyrolactone, gamma-	96-48-0	2.21 E-05	3.11	31100	0.03	340
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	2.21 E-05	3.11	31100	0.03	340
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	2.21 E-05	3.11	31100	0.03	340
Other organic materials	Organosilane	TS ref# 10001	2.21 E-05	3.11	31100	0.03	340
Other inorganic materials	Copper(II) oxide	1317-38-0	2.21 E-05	3.11	31100	0.03	340
Other organic materials	Epoxy resin modifier	TS ref# 10038	3.69 E-06	0.52	5200	0.01	57
Subtotal			7.10 E-04	100.0	1000000	1.09	10943

	Weight (g)	Percentage (%)	PPM
Package Totals	**6.49 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

Product / Package Information

Package	LFCSP - Punched
Body Size (mm)	5 X 5 X 0.85 (3.1 EP)
Lead Count	16
Terminal Finish	85Sn/15Pb

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.18E-02	86.91	869100	33.68	336763
Thermosets	Epoxy & Phenol Resin	Proprietary	3.21E-03	12.78	127800	4.95	49521
Other inorganic materials	Carbon black	1333-86-4	7.79E-05	0.31	3100	0.12	1201
Subtotal			2.51 E-02	100.00	1000000	38.75	387485

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
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Copper & its alloys	Iron	7439-89-6	8.37 E-04	2.50	25006	1.29	12904
Copper & its alloys	Zinc	7440-66-6	2.01 E-04	0.60	6004	0.31	3098
Copper & its alloys	Phosphorus	7723-14-0	1.67 E-04	0.50	5001	0.26	2581
Subtotal			3.35 E-02	100.00	1000000	51.60	516030

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.40 E-04	100.0	1000000	1.14	11406

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	9.27 E-04	85.0	850000	1.43	14280
Tin & its alloys	Lead	7439-92-1	1.64 E-04	15.0	150000	0.25	2520
Subtotal			1.09 E-03	100.0	1000000	1.68	16800

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.40 E-04	100.0	1000000	0.83	8323

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.18 E-03	100.0	1000000	4.90	49014

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
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Precious metals	Silver	7440-22-4	5.52 E-04	77.71	777100	0.85	8504
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	2.21 E-05	3.11	31100	0.03	340
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	2.21 E-05	3.11	31100	0.03	340
Other organic materials	Butyrolactone, gamma-	96-48-0	2.21 E-05	3.11	31100	0.03	340
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	2.21 E-05	3.11	31100	0.03	340
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	2.21 E-05	3.11	31100	0.03	340
Other organic materials	Organosilane	TS ref# 10001	2.21 E-05	3.11	31100	0.03	340
Other inorganic materials	Copper(II) oxide	1317-38-0	2.21 E-05	3.11	31100	0.03	340
Other organic materials	Epoxy resin modifier	TS ref# 10038	3.69 E-06	0.52	5200	0.01	57
Subtotal			7.10 E-04	100.0	1000000	1.09	10943

	Weight (g)	Percentage (%)	PPM
Package Totals	**6.49 E-02**	**100**	**1000000**